L Number	Hits	Search Text	DB	Time stamp
		//i	USPAT;	2003/06/18
239	,1	((semiconductor rs mi\$1conductor) n ar3		15:04
		dynamic) with (adhesive near3 film)	US-P PUB	
241	28	((semiconductor or semi\$1conductor) n ar3	USPAT;	2003/06/18
		dynamic) and (adhesive near3 film)	US-P PUB	15:10
242	17	(dynamic near3 (sensor or detector)) and	USPAT;	2003/06/18
		(adhesive near3 film)	US-PGPUB	15:30
243	7	(sensor near3 chip) with (adhesive near3	USPAT;	2003/06/18
		film)	US-PGPUB	15:56
244	7	("5266827" "5656711" "5747694"	USPAT	2003/06/18
		"6034421" "6040400" "6121359"		15:32
		"6127504").PN.		
249	2	(sensor near3 chip) near5 (adhesive near3	USPAT;	2003/06/18
	_	film) near4 (substrate)	US-PGPUB	16:00
250	2	(sensor near3 chip) with ((adhesive near3	USPAT;	2003/06/18
	4	film) or (polymide near3 resin)) near4	US-PGPUB	16:01
		(substrate)	30.0.00	
254	5	(supstrate) (sensor near3 chip) with ((adhesive near3	EPO; JPO;	2003/06/18
251	5		DERWENT	16:25
		film) or (polymide near3 resin))		10120
255	9	((sensor near3 chip) near3 (coupl\$3 or	USPAT;	2003/06/18
		attach\$3 or connect\$4 or laminat\$3 or	US-PGPUB	16:41
		mount\$3) near3 ((circuit near chip) or		
		substrate)) and (adhesive near3 film)		
256	47	((sensor near3 chip) same ((circuit near3	USPAT;	2003/06/18
		chip) or substrate)) and ((adhesive near3	US-PGPUB	17:12
		film) or (polymide near3 resin))		
257	4652	((circuit near3 chip) or substrate) with	USPAT;	2003/06/18
		((adhesive near3 film) or (polymide near3	US-PGPUB	17:14
		resin))		
258	937	(((circuit near3 chip) or substrate) near4	USPAT;	2003/06/18
		(mount\$3 on attach\$3 or connect\$ or	US-PGPUB	17:19
		interpose\$3 or laminat\$3)) with ((adhesive		
		near3 film) or (polymide near3 resin))		
260	1	(((circuit near3 chip) or substrate) with	USPAT;	2003/06/18
260	1	((adhesive near3 film) or (polymide near3	US-PGPUB	17:22
		1 **	33-FGF0B	11:22
	_	resin))) same (dynamic near3 sensor)	HEDAT:	2003/06/18
259	8	(((circuit near3 chip) or substrate) with	USPAT;	1
		((adhesive near3 film) or (polymide near3	US-PGPUB	17:22
		resin))) same (acceleration)		
261	2	((((circuit near3 chip) or substrate) near4	USPAT;	2003/06/18
		(mount\$3 on attach\$3 or connect\$ or	US-PGPUB	17:23
		interpose\$3 or laminat\$3)) with ((adhesive		
		near3 film) or (polymide near3 resin))) same		
		(acceleration)		
262	2	((((circuit near3 chip) or substrate) near4	USPAT;	2003/06/18
		(mount\$3 on attach\$3 or connect\$ or	US-PGPUB	17:24
		interp se\$3 or laminat\$3)) with ((adhesive		
		near3 film) r (polymid near3 resin))) same		
		(sensor near3 chip)	1	

263	10	((sensor near3 chip) n ar3 (coupl\$3 or	USPAT;	2003/06/18
		attach\$3 or connect\$4 or laminat\$3 or	US-P PUB	17:28
		mount\$3) near3 ((circuit near3 chip) or		
		substrat)) and (adhesive near3 film)		
264	11	((sensor near3 chip) near3 (coupl\$3 or	USPAT;	2003/06/18
		attach\$3 or connect\$4 or laminat\$3 or	US-PGPUB	18:04
		mount\$3) near3 ((circuit near3 chip) or		
		substrate)) and ((adhesive near3 film) or		
		polyimide near3 adhesive)		
265	0	(stack\$3 near3 microchip) with ((adhesive	USPAT;	2003/06/18
		near3 film) or (polyimide near3 adhesive))	US-PGPUB	18:05
266	5	(stack\$3 near3 microchip) and ((adhesive	USPAT;	2003/06/18
		near3 film) or (polyimide near3 adhesive))	US-PGPUB	18:07
267	30	(stack\$3 near3 microchip) and ((adhesive	USPAT;	2003/06/18
		near3 film) or ((polyimide or polymer) near3	US-PGPUB	18:09
		(adhesive or film)))		